# October 22 (Thu.), 2026

## [Oral 11] CMP Consumables (II)

11:25-12:45

International Conference Hall (B1F)

● Session Chair: Andy Tuan (Linx Consulting Inc., Taiwan)

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| 11:25-11:45<br>[Oral 11-1] | The Interconnect Advantage: CMP Powering AI and HBM<br><br>Ping Tzeng, Jingzhi Chen (Merck, Taiwan), and Hongjun Zhou (The Electronics Business of Merck KGaA, Germany) |
| 11:45-12:05<br>[Oral 11-2] | Study on the Mechanism of unCMP Caused by Plastic Deformation of the Head Membrane in CMP Equipment and Its Improvement<br><br>KyongKyu Myong, Jubong Lee, Younggeun Lee, Yoo-Yong Lee, Ki Ho Bae, and Hoyoung Kim (Samsung Electronics Co., Ltd., Korea) |
| 12:05-12:25<br>★[Oral 11-3] | Identifying the Origin of Small Particle Defects in Oxide Chemical Mechanical Planarization<br><br>Seungmoon Choi, Hyeonjeong Lee, Hyunho Kim, Junil Cho, and Taesung Kim (Sungkyunkwan Univ., Korea) |
| 12:25-12:45<br>[Oral 11-4] | New Particle and Chemistry Technology for Metals IC CMP Slurries<br><br>Yu Yu Chou, Howl Hsu (Entegris Co., Ltd., Taiwan), Brian Reiss, and Na Zhang (Entegris Inc., USA) |